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TOLERANCES UNLESS OTHERWISE SPECIFIED		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		<div><div></div><div>maxim integrated™</div></div>	
FRACTIONS +/- $\frac{\quad}{\quad}$		DECIMALS .XX +/- .01 .XXX +/- .005		ANGLES +/- $\frac{\quad}{\quad}$	
MATERIAL:  SEE NOTES		DRAWN BY: KA DATE: 06/16/2020		HARDWARE NAME:  MAX3307IE_SHIELD_EVKIT_B	
FINISH:  SEE NOTES		CHECKED BY: DATE: APPR. BY: DATE: APPR. BY: DATE:		HARDWARE NUMBER: XX-XXXX-XXX NOT TO SCALE TEMPLATE REV:	
				REV B SHEET 1 OF 1	

REVISIONS			
REV	DESCRIPTION	APPROVED	DATE

- NOTES:
- UNLESS OTHERWISE SPECIFIED
1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
- MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)
2. BOARD MATERIAL:
- (X) ISOLA 370HR OR EQUIVALENT
- ( ) ISOLA-FR408HR OR EQUIVALENT
- ( ) NELCO-4000-13
- ( ) MEGTRON 6
- ( ) ROGERS 4350B
- ( ) ROGERS 4003C
- ( ) OTHER \_\_\_\_\_
3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.
- WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATING OF 94V-0.
5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH. BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
- TOOLING:
7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER R52T4X OR ODB++ FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNC DRILL FILE.
8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS AND TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, VENDOR MUST FOLLOW AND MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENTS MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM MAXIM.
9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
- ( ) FILLETED
- (X) NOT FILLETED
10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES. LEGEND TO LEGEND +/- 0.007 INCHES
11. FINISHED COPPER WEIGHT/THICKNESS:
- (X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIREMENTS. THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE, UNLESS OTHERWISE SPECIFIED.
- ( ) OTHER \_\_\_\_\_
- SURFACE FINISH:
12. USE CHECKED ITEMS FOR PLATING
- ( ) ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (KNOOP HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C. GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0. CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-600 MICROINCHES THICK).
- (X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
- ( ) FINGERS TO BE GOLD PLATED.
- ( ) OTHER \_\_\_\_\_
13. DRELL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP UNLESS SPECIFIED. MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED ON UNFILLED VIA IN PAD HOLES.
- SOLDERMASK:
14. SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE (LPI) INK
- (X) CUSTOM MAXIM TEAL SOLDER MASK. PANTONE #326C.
- ( ) OTHER \_\_\_\_\_
- SILKSCREEN:
15. APPLY SILKSCREEN USING A NON-CONDUCTIVE EPOXY INK
- (X) WHITE
- ( ) OTHER \_\_\_\_\_
16. VENDOR LOGO & DATE CODE REQUIREMENT. DATE CODE FORMAT MUST BE YYWW ONLY
- (X) PLACE ON BOTTOM LEGEND LAYER. IF NO BOTTOM LEGEND SUPPLIED, CREATE BOTTOM LEGEND LAYER TO ADD.
- ( ) PLACE ON TOP LEGEND LAYER. IF NO TOP LEGEND SUPPLIED, CREATE TOP LEGEND LAYER TO ADD.
- ( ) OTHER \_\_\_\_\_
- TESTING:
17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)
- THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.
- MISCELLANEOUS:
19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY. UNLESS OTHERWISE SPECIFIED.
20. FOR ALL DRILL INFORMATION REFER TO DRILL CHART.
- ( ) NON-CONDUCTIVE EPOXY FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
- ( ) SILVER FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES PROBE MARKS OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.
22. THEEVING:
- ( ) SUPPLIER MAY ADD THEEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
- (X) SUPPLIER MAY NOT ADD THEEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
23. PENNUT
- ( ) PENNUTS TO BE INSTALLED BY FABRICATOR.
- ( ) PENNUTS NOT TO BE INSTALLED BY FABRICATOR.
- (X) NOT APPLICABLE.

